MICROCHIP

Semiconductor Device Type: **6AX-SOT-23-6-NiPdAu**

Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm
Die	Silicon	7440-21-3	2.85	7.64	28497
Mold Compound	Silica (Crystalline)	60676-86-0	54.48	146.05	544752
Mold Compound	Phenolic Resin	Trade Secret (or various)	5.35	14.34	53473
Mold Compound	Epoxy Resin	Trade Secret (or various)	6.68	17.92	66841
Mold Compound	Carbon Black	1333-86-4	0.33	0.90	3342
Die Attach	Silver	7440-22-4	0.20	0.54	2029
Die Attach	Carbocyclic Acrylate	Trade Secret (or various)	0.06	0.16	597
Die Attach	Bismaleimide Resin	Trade Secret (or various)	0.01	0.04	149
Die Attach	Acrylate	Trade Secret (or various)	0.01	0.04	149
Die Attach	Epoxycyclohexylethyltrimethoxysilane	543576	0.00	0.01	30
Die Attach	Palladium Compound	Trade Secret (or various)	0.00	0.01	30
Bond Wire	Gold	7440-57-5	0.24	0.64	2387
Lead Plating	Tin	7440-31-5	2.05	5.49	20494
Lead Plating	Other	Trade Secret	0.00	0.01	21
Lead Frame Plating	Silver	7440-22-4	0.45	1.20	4476
Lead Frame	Nickel	7440-02-0	0.88	2.36	8785
Lead Frame	Copper	7440-50-8	26.15	70.10	261479
Lead Frame	Silicon	7440-21-3	0.20	0.53	1990
Lead Frame	Magnesium	7439-95-4	0.05	0.13	480
		TOTALS:	**100.00**	**268.10**	**1,000,000**

268.10 mg Total Mass

Package Homogeneous Materials

7.64	(mg) Total	Die	% of Total Weight	2.85
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
179.20	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**66.84**
	Silica (Crystalline)	60676-86-0	81.50	
	Phenolic Resin	Trade Secret (or various)	8.00	
	Epoxy Resin	Trade Secret (or various)	10.00	
	Carbon Black	1333-86-4	0.50	
		Total	**100.00**	
0.80	**(mg) Total**	**Die Attach**	**% of Total Weight**	**0.30**
	Silver	7440-22-4	68.00	
	Carbocyclic Acrylate	Trade Secret (or various)	20.00	
	Bismaleimide Resin	Trade Secret (or various)	5.00	
	Acrylate	Trade Secret (or various)	5.00	
	Epoxycyclohexylethyltrimethoxysilane	543576	1.00	
	Palladium Compound	Trade Secret (or various)	1.00	
		Total	**100.00**	
0.64	**(mg) Total**	**Bond Wire**	**% of Total Weight**	**0.24**
	Gold	7440-57-5	100.00	
		Total	**100.00**	
5.50	**(mg) Total**	**Lead Plating**	**% of Total Weight**	**2.05**
	Tin	7440-31-5	99.90	
	Other	Trade Secret	0.10	
		Total	**100.00**	
1.20	**(mg) Total**	**Lead Frame Plating**	**% of Total Weight**	**0.45**
	Silver	7440-22-4	100.00	
		Total	**100.00**	
73.12	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**27.27**
	Nickel	7440-02-0	3.22	
	Copper	7440-50-8	95.87	
	Silicon	7440-21-3	0.73	
	Magnesium	7439-95-4	0.18	
268.10		**Total**	**100.00**	**100.00**

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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